

## IC Substrate Technics Capacity

No.	Item	Description	DataSheet
1	Sheng Yi	Core/P.P	SI643HU, SI10U, SI09U, SI07U, SI05U
2	Mitsubishi Gas Chemical	Core/P.P	HL832NXA, HL832NS, HL832NSR(LC)
3	DooSan	Core/P.P	DS-7409HGB(S), DS-7409HGB(LE), DS-7409HGB(X)
4	Panasonic	Core/P.P	R1515E/R1515H
5	Other Materials	Core/P.P	E679FGB, E770G(LH), BT-NSF(LCA)
6	Layer	Layer	1-16layer
7	Min pattern size	um	25
8	Min pattern Space	um	25
9	Min Pad	um	80
10	Min BGA Center Space	um	250
11	2L Min Thickness	um	80
12	2L Min thickness/core/PP Thickness	um	80/30
13	4L Min thickness/core/PP Thickness	um	200/50/20
14	6L Min thickness/core/PP Thickness	um	240/50/20
15	8L Min thickness/core/PP Thickness	um	330/50/20

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16	Solder mask Color		Green,Black
17	Solder resist		EG23A, AUS308, AUS320, AUS410
18	Surface treatment		Soft Gold Plating,Hard Gold Plating,ENIG,OSP
19	Flatness	um	5max
20	Min hole size	wn	100
21	Min Laser hole size	um	50
22	Min thickness tolerance	um	30
23	Min PP	um	25
24	Min Core	um	40
25	Minimum Finger Center Distance	um	65
26	Min para-position accuracy	um	15
27	Support Process		Subtraction process, mSAP Process
28	Soldermask tolerance	um	5